



CYPRESS

CYM1441

## 256K x 8 Static RAM Module

## Features

- **High-density 2-megabit SRAM module**
- **High-speed CMOS SRAMs**  
— Access time of 20 ns
- **Low active power**  
— 5.3W (max.)
- **SMD technology**
- **Separate data I/O**
- **60-pin ZIP package**
- **TTL-compatible inputs and outputs**
- **Low profile**  
— Max. height of 0.5 in.
- **Small PCB footprint**  
— 1.14 sq. in.

## Functional Description

The CYM1441 is a very high performance 2-megabit static RAM module organized as 256K words by 8 bits. The module is constructed using eight 256K x 1 static RAMs in SOJ packages mounted onto an epoxy laminate substrate with pins. Two chip selects ( $\overline{CS}_L$  and  $\overline{CS}_U$ ) are used to independently enable the upper and lower 4 bits of the data word.

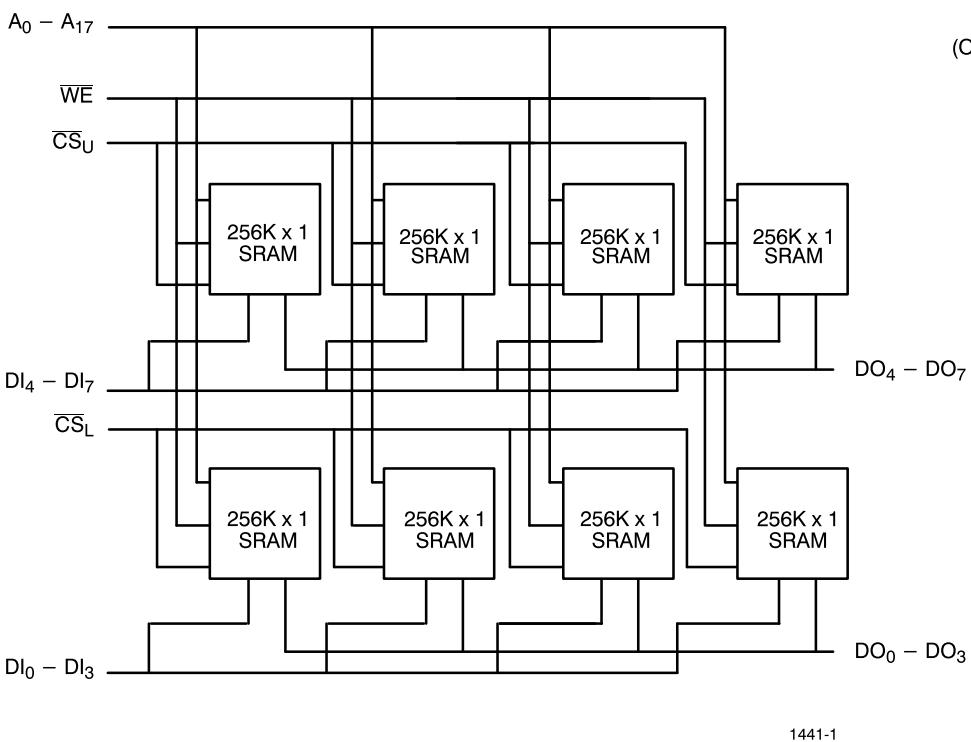
Writing to the memory module is accomplished when the chip select ( $\overline{CS}$ ) and write enable ( $\overline{WE}$ ) inputs are both LOW. Data on the eight input pins ( $DI_0$  through  $DI_7$ ) is written into the memory location specified on the address pins ( $A_0$  through  $A_{17}$ ).

Reading the device is accomplished by taking chip select ( $\overline{CS}$ ) LOW while write enable ( $\overline{WE}$ ) remains inactive or HIGH. Under these conditions, the contents of the memory location specified on the address pins will appear on the appropriate data output pins ( $DO_0$  through  $DO_7$ ).

The data output pins remain in a high-impedance state unless the module is selected and write enable ( $\overline{WE}$ ) is HIGH.

Two pins ( $PD_0$  and  $PD_1$ ) are used to identify module memory density in applications where alternate versions of the JEDEC-standard modules can be interchanged.

## Logic Block Diagram



## Pin Configuration

ZIP Top View	
(OPEN)	PD <sub>0</sub>
NC	2 GND
V <sub>CC</sub>	3 PD <sub>1</sub> (GND)
DI <sub>0</sub>	4 NC
DO <sub>0</sub>	5 NC
A <sub>0</sub>	6 NC
A <sub>2</sub>	7 NC
A <sub>4</sub>	8 NC
A <sub>6</sub>	9 NC
GND	10 NC
DI <sub>1</sub>	11 NC
DO <sub>1</sub>	12 NC
WE	13 NC
A <sub>9</sub>	14 NC
CS <sub>L</sub>	15 NC
DI <sub>4</sub> – DI <sub>7</sub>	16 NC
DO <sub>4</sub> – DO <sub>7</sub>	17 NC
DI <sub>0</sub> – DI <sub>3</sub>	18 NC
DO <sub>0</sub> – DO <sub>3</sub>	19 NC
	20 NC
	21 NC
	22 NC
	23 NC
	24 NC
	25 NC
	26 V <sub>CC</sub>
	27 A <sub>8</sub>
	28 NC
	29 NC
	30 NC
	31 NC
	32 NC
	33 NC
	34 NC
	35 NC
	36 NC
	37 NC
	38 NC
	39 NC
	40 NC
	41 GND
	42 A <sub>10</sub>
	43 A <sub>11</sub>
	44 A <sub>12</sub>
	45 A <sub>13</sub>
	46 A <sub>14</sub>
	47 A <sub>15</sub>
	48 A <sub>16</sub>
	49 A <sub>17</sub>
	50 NC
	51 NC
	52 NC
	53 NC
	54 NC
	55 NC
	56 NC
	57 NC
	58 NC
	59 NC
	60 NC

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## Selection Guide

	1441-20	1441-25	1441-35	1441-45
Maximum Access Time (ns)	20	25	35	45
Maximum Operating Current (mA)	960	960	960	960
Maximum Standby Current (mA)	320	320	320	320

Shaded area contains preliminary information.

## Maximum Ratings

**Maximum Ratings**  
(Above which the useful life may be impaired.)

Storage Temperature .....	-55°C to +125°C
Ambient Temperature with Power Applied .....	-10°C to +85°C
Supply Voltage to Ground Potential .....	-0.5V to +7.0V
DC Voltage Applied to Outputs in High Z State .....	-0.5V to +7.0V
DC Input Voltage .....	-0.5V to +7.0V

## Operating Range

Range	Ambient Temperature	V <sub>CC</sub>
Commercial	0°C to +70°C	5V ± 10%

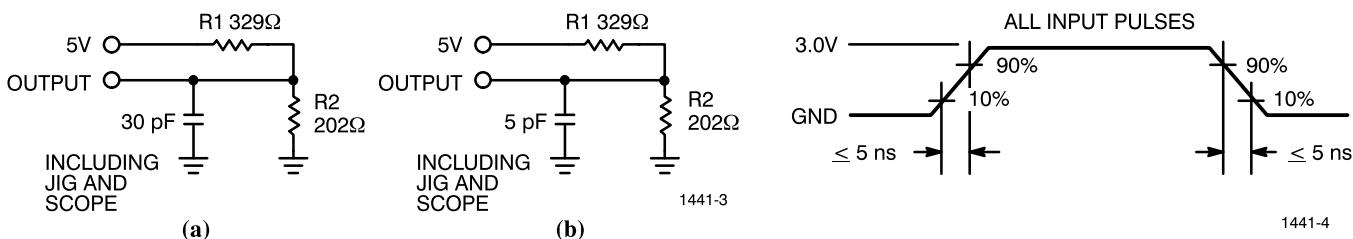
## Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	Min.	Max.	Unit
V <sub>OH</sub>	Output HIGH Voltage	V <sub>CC</sub> = Min., I <sub>OH</sub> = -4.0 mA	2.4		V
V <sub>OL</sub>	Output LOW Voltage	V <sub>CC</sub> = Min., I <sub>OL</sub> = 12.0 mA		0.4	V
V <sub>IH</sub>	Input HIGH Voltage		2.2	V <sub>CC</sub>	V
V <sub>IL</sub>	Input LOW Voltage <sup>[1]</sup>		-0.5	0.8	V
I <sub>IX</sub>	Input Load Current	GND ≤ V <sub>I</sub> ≤ V <sub>CC</sub>	-80	+80	µA
I <sub>OZ</sub>	Output Leakage Current	GND ≤ V <sub>O</sub> ≤ V <sub>CC</sub> , Output Disabled	-50	+50	µA
I <sub>CC</sub>	V <sub>CC</sub> Operating Supply Current	V <sub>CC</sub> = Max., I <sub>OUT</sub> = 0 mA, CS ≤ V <sub>IL</sub>		960	mA
I <sub>SB1</sub>	Automatic CS Power-Down Current	Max. V <sub>CC</sub> , CS ≥ V <sub>IH</sub> , Min. Duty Cycle = 100%		320	mA
I <sub>SB2</sub>	Automatic CS Power-Down Current	Max. V <sub>CC</sub> , CS ≥ V <sub>CC</sub> - 0.2V, V <sub>IN</sub> ≥ V <sub>CC</sub> - 0.2V or V <sub>IN</sub> ≤ 0.2V		160	mA

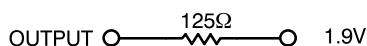
## Capacitance<sup>[2]</sup>

Parameter	Description	Test Conditions	Max.	Unit
$C_{IN}$	Input Capacitance	$T_A = 25^\circ C$ , $f = 1$ MHz, $V_{CC} = 5.0V$	60	pF
$C_{OUT}$	Output Capacitance		15	pF

## AC Test Loads and Waveforms



Equivalent to: THÉVENIN EQUIVALENT



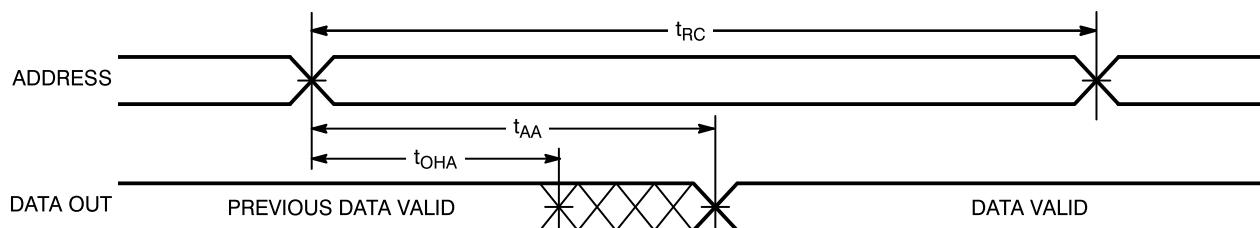
## Notes:

1.  $V_{IN}$  (min.) = - 3.0V for pulse widths less than 20 ns. 2. Tested on a sample basis.

**Switching Characteristics** Over the Operating Range<sup>[3]</sup>

Parameter	Description	1441-20		1441-25		1441-35		1441-45		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
<b>READ CYCLE</b>										
$t_{RC}$	Read Cycle Time	20		25		35		45		ns
$t_{AA}$	Address to Data Valid		20		25		35		45	ns
$t_{OHA}$	Data Hold from Address Change	3		3		3		3		ns
$t_{ACS}$	$\overline{CS}$ LOW to Data Valid		20		25		35		45	ns
$t_{LZCS}$	$\overline{CS}$ LOW to Low Z	3		3		3		3		ns
$t_{HZCS}$	$\overline{CS}$ HIGH to High Z <sup>[4]</sup>		12		15		25		30	ns
$t_{PU}$	$\overline{CS}$ LOW to Power-Up	0		0		0		0		ns
$t_{PD}$	$\overline{CS}$ HIGH to Power-Down		20		25		35		45	ns
<b>WRITE CYCLE<sup>[5]</sup></b>										
$t_{WC}$	Write Cycle Time	20		25		35		45		ns
$t_{SCS}$	$\overline{CS}$ LOW to Write End	15		20		30		35		ns
$t_{AW}$	Address Set-Up to Write End	15		20		30		35		ns
$t_{HA}$	Address Hold from Write End	2		2		2		2		ns
$t_{SA}$	Address Set-Up to Write Start	0		0		0		2		ns
$t_{PWE}$	$\overline{WE}$ Pulse Width	15		20		25		30		ns
$t_{SD}$	Data Set-Up to Write End	13		15		20		20		ns
$t_{HD}$	Data Hold from Write End	0		0		0		0		ns
$t_{LZWE}$	$\overline{WE}$ HIGH to Low Z	3		3		3		3		ns
$t_{HZWE}$	$\overline{WE}$ LOW to High Z <sup>[4]</sup>	0	13	0	15	0	20	0	25	ns

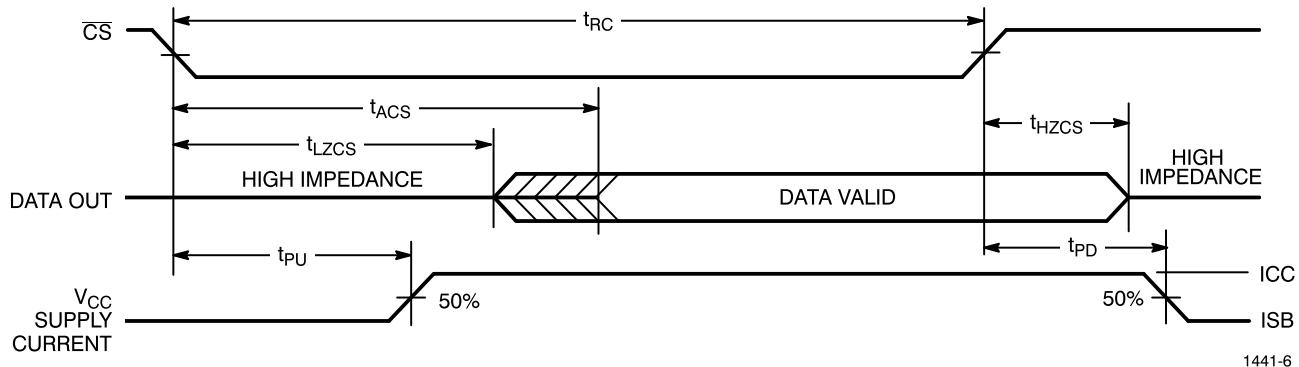
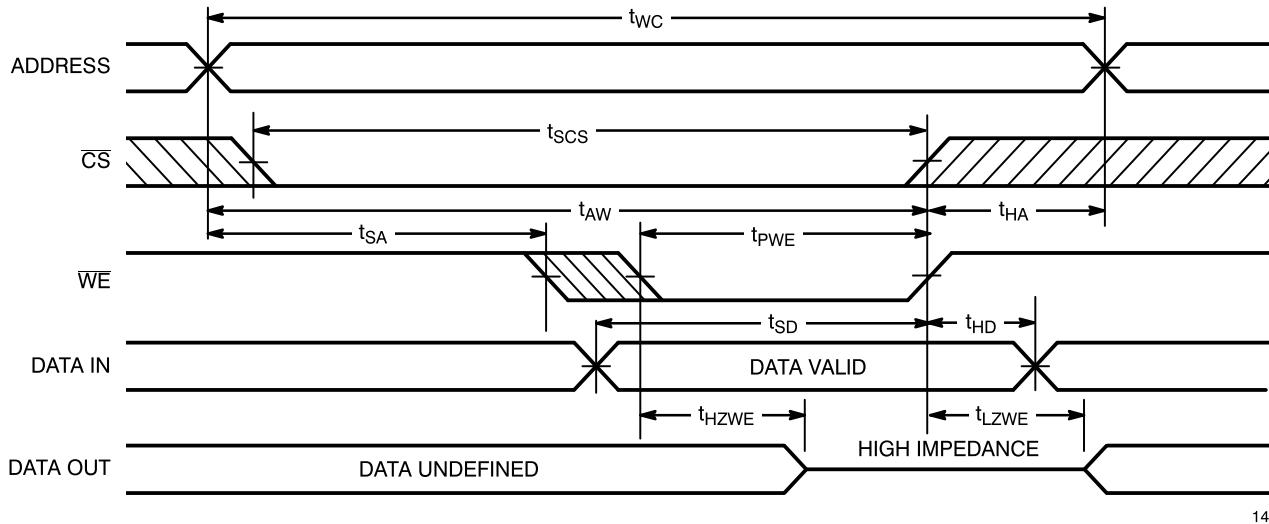
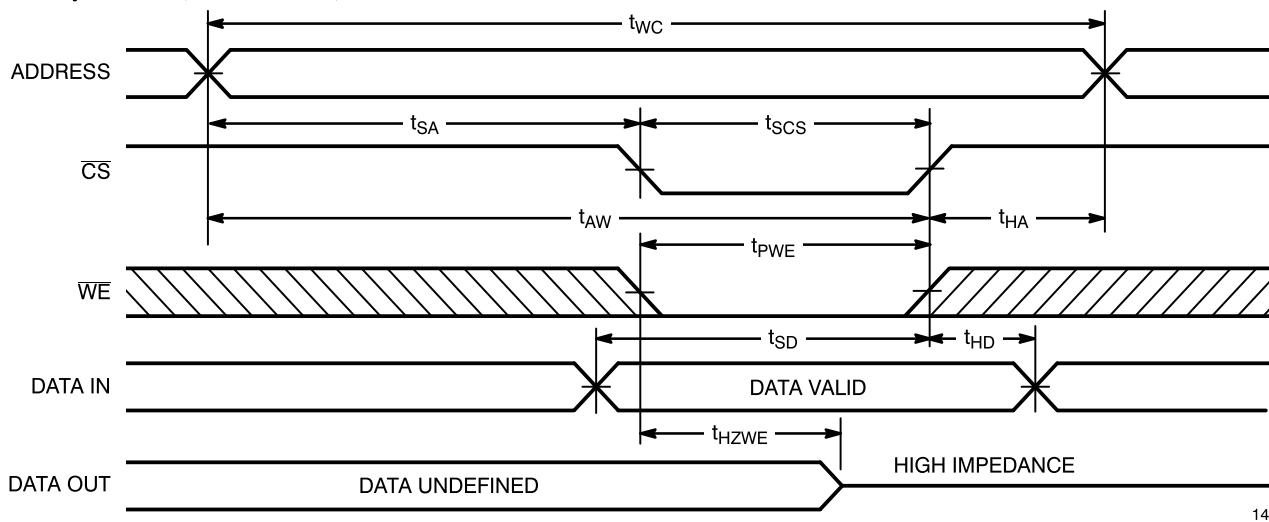
Shaded area contains preliminary information.

**Switching Waveforms**
**Read Cycle No. 1<sup>[6, 7]</sup>**


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**Notes:**

3. Test conditions assume signal transition times of 5 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified  $I_{OL}/I_{OH}$  and 30-pF load capacitance.
4.  $t_{HZCS}$  and  $t_{HZWE}$  are specified with  $C_L = 5$  pF as in part (b) of AC Test Loads and Waveforms. Transition is measured  $\pm 500$  mV from steady state voltage.
5. The internal write time of the memory is defined by the overlap of  $\overline{CS}$  LOW and  $\overline{WE}$  LOW. Both signals must be LOW to initiate a write and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.
6.  $WE$  is HIGH for read cycle.
7. Device is continuously selected,  $\overline{CS} = V_{IL}$ .

**Switching Waveforms (continued)**
**Read Cycle No. 2<sup>[6, 8]</sup>**

**Write Cycle No. 1 ( $\overline{WE}$  Controlled)<sup>[5]</sup>**

**Write Cycle No. 2 ( $\overline{CS}$  Controlled)<sup>[5, 9]</sup>**

**Notes:**

8. Address valid prior to or coincident with  $\overline{CS}$  transition LOW.

9. If  $\overline{CS}$  goes HIGH simultaneously with  $\overline{WE}$  HIGH, the output remains in a high-impedance state.

**Truth Table**

CS	WE	Input/Output	Mode
H	X	High Z	Deselect/Power-Down
L	H	Data Out	Read
L	L	Data In	Write

**Ordering Information**

Speed	Ordering Code	Package Name	Package Type	Operating Range
20	CYM1441PZ-20C	PZ04	60-Pin ZIP Module	Commercial
25	CYM1441PZ-25C	PZ04	60-Pin ZIP Module	Commercial
35	CYM1441PZ-35C	PZ04	60-Pin ZIP Module	Commercial
45	CYM1441PZ-45C	PZ04	60-Pin ZIP Module	Commercial

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**Package Diagrams**
**60-Pin ZIP Module PZ04**
